

Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	20
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	8.24 E-01	87.7	877000	58.30		582962
Thermosets	Epoxy Resin	Proprietary	4.70 E-02	5.0	50000	3.32		33236
Thermosets	Phenol Resin	Proprietary	4.70 E-02	5.0	50000	3.32		33236
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.88 E-02	2.0	20000	1.33		13294
Other inorganic materials	Carbon Black	1333-86-3	2.82 E-03	0.3	3000	0.20		1994
Subtotal			9.40 E-01	100	1000000	66.47		664723
Leadframe								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	4.30 E-01	97.57	975706	30.43		304309
Copper & its alloys	Iron	7439-89-6	1.00 E-02	2.28	22789	0.71		7108
Copper & its alloys	Zinc	7440-66-6	5.57 E-04	0.13	1263	0.04		394
Copper & its alloys	Phosphorus	7723-14-0	1.07 E-04	0.02	242	0.01		76
Subtotal			4.41 E-01	100.00	1000000	31.19		311886
Internal Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	9.21 E-04	100.0	1000000	0.07		652
External Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	2.21 E-02	100.0	1000000	1.56		15600
Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	2.46 E-04	99.99	1000000	0.02		174
Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	9.08 E-03	100.0	1000000	0.64		6422
Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	6.14 E-04	80	800000	0.04		434
Thermosets	Epoxy Resin	Proprietary	1.15 E-04	15	150000	0.01		81
Others	Curing agent & hardener	Proprietary	3.83 E-05	5	50000	0.00		27
Subtotal			7.67 E-04	100	1000000	0.05		542
Package Totals			Weight (g)			Percentage (%)	PPM	1000000
			1.41 E+00			100.00		

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	20
Terminal Finish	85Sn15Pb

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration
Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.24 E-01	87.7	877000	58.30	582962
Thermosets	Epoxy Resin	Proprietary	4.70 E-02	5.0	50000	3.32	33236
Thermosets	Phenol Resin	Proprietary	4.70 E-02	5.0	50000	3.32	33236
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.88 E-02	2.0	20000	1.33	13294
Other inorganic materials	Carbon Black	1333-86-3	2.82 E-03	0.3	3000	0.20	1994
Subtotal			9.40 E-01	100	1000000	66.47	664723

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.30 E-01	97.57	975706	30.43	304309
Copper & its alloys	Iron	7439-89-6	1.00 E-02	2.28	22789	0.71	7108
Copper & its alloys	Zinc	7440-66-6	5.57 E-04	0.13	1263	0.04	394
Copper & its alloys	Phosphorus	7723-14-0	1.07 E-04	0.02	242	0.01	76
Subtotal			4.41 E-01	100.00	1000000	31.19	311886

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.21 E-04	100.0	1000000	0.07	652

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.87 E-02	85.0	850000	1.33	13260
Tin & its alloys	Lead	7439-92-1	3.31 E-03	15.0	150000	0.23	2340
Subtotal			2.21 E-02	100.0	1000000	1.56	15600

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.46 E-04	99.99	1000000	0.02	174

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.08 E-03	100.0	1000000	0.64	6422

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
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Precious metals	Silver	7440-22-4	6.14 E-04	80	800000	0.04	434
Thermosets	Epoxy Resin	Proprietary	1.15 E-04	15	150000	0.01	81
Others	Curing agent & hardener	Proprietary	3.83 E-05	5	50000	0.00	27
Subtotal			7.67 E-04	100	1000000	0.05	542

Package Totals	Weight (g)	Percentage (%)	PPM
	1.41 E+00	100.00	1000000

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